# **MRS Ballot Results are Final**

In the yearly election that just ended October 15, 1993, MRS members elected three officers and three councillors to join 1994 MRS President John C. Bravman of Stanford University.

MRS members also ratified the changes to Article II of the MRS Constitution. The status of Retired Member no longer requires a three-year membership in MRS, and the status of Unemployed Member was established. The text for these changes appears on page 28 of the 1993 MRS Membership Directory.

# 1994 MRS Officers

#### President

John C. Bravman (1994) Stanford University

# **Immediate Past President**

S. Thomas Picraux (1994) Sandia National Laboratories

### First Vice President (President Elect)

\*Julia M. Phillips (1994) AT&T Bell Laboratories

#### Second Vice President

\*Carl V. Thompson (1994) Massachusetts Institute of Technology

#### Secretary

\*Carl C. Koch (1995) North Carolina State University

#### Treasurer

A. Kay Hays (1994) Sandia National Laboratories

# 1994 MRS Councillors

Bill R. Appleton (1995) Oak Ridge National Laboratories

\*Howard K. Birnbaum (1996) University of Illinois

Aaron N. Bloch (1994) State University of New York-Buffalo

R.P.H. Chang (1994) Northwestern University

Russell R. Chianelli (1994) Exxon Research and Engineering

Clifton W. Draper (1995) AT&T - ERC Merton C. Flemings (1995) Massachusetts Institute of Technology

J. Murray Gibson (1995) University of Illinois-Urbana

Robert Hull (1994) AT&T Bell Laboratories

Carol M. Jantzen (1994) Westinghouse Savannah River Company

\*Kevin S. Jones (1996) University of Florida

\*Merrilea J. Mayo (1996) Pennsylvania State University

June D. Passaretti (1995) Minerals Technologies

Paul S. Peercy (1994) Sandia National Laboratories

Richard W. Siegel (1995) Argonne National Laboratory

(Terms of office expire at the end of the years indicated in parentheses.)

\*Newly Elected



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